L Number	Hits	Search Text	DB	Time stamp
7	0	"042954"	JPO	2003/01/12 18:41
8	0	"59-042954"	JPO	2003/01/12 18:41
9	0	"002128554"	JPO	2003/01/12 18:41
10	0	"097690"	JPO	2003/01/12 18:41
11	0	"0154104"	JPO	2003/01/12 18:41
12	373896	laminate board produce attach	JPO	2003/01/12 18:41
13	692411	includes attaching thermally insulated plates to edge of hot plates	JPO	2003/01/12 18:41
14	0	"includes attaching thermally insulated plates to edge of hot plates"	JPO	2003/01/12 18:41
15	0	includes and attaching and thermally and insulated and plates and to and edge and of and hot and plates	JPO	2003/01/12 18:41
16	0	(matsushita) and laminate and board and thermal and insulate and plate	JPO	2003/01/12 18:41
17	0	laminate and board and thermal and insulate and plate	JPO	2003/01/12 18:41
1	205	156/$.ccls. and press and (heat or heating) and (cool or cooling) and (ID or identification)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:42
2	25	100/$.ccls. and press and (heat or heating) and (cool or cooling) and (ID or identification)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:42
3	383	(156/300).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:42
4	417	(156/303.1).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:42
5	342	(156/312).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:42
6	977	((156/583.1) or (156/583.2)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:11
18	4	board and thermal and insulate and plate	JPO	2003/01/12 18:43
19	41	board and thermal and laminate and plate	JPO	2003/01/12 18:43
21	183	(156/381).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:43
22	328	((156/559) or (156/563)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:43
20	895	((156/299) or (156/300)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 18:47

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23	460	(156/581).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:28
24	46	(100/305).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:30
25	86	(100/315).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:36
26	35	(100/316).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:39
27	39	(100/317).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:40
28	18	(100/318).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:44
29	83	(100/319).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:48
30	57	(100/321).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:51
31	58	(100/322).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/12 19:51

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